

**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of:

YAMAMOTO et al.

Group Art Unit: Unknown

Application No.: Not yet Assigned

Examiner: Unknown

Filed: February 26, 2002

Attorney Dkt. No.: 108384-00043

For: MANUFACTURING PROCESS FOR PRINTED WIRING BOARD

**PRELIMINARY AMENDMENT**

Commissioner for Patents  
Washington, D.C. 20231

February 26, 2002

Sir:

Prior to initial examination of the application, please amend the above-identified application as follows:

**IN THE CLAIMS:**

Please amend claims 9-11 as follows:

9. (Amended) The manufacturing process for a printed wiring board according to claim 5, characterized in that said organic layer is formed with one or two selected from the group consisting of nitrogen-containing organic compounds, sulfur-containing organic compounds and carboxylic acids.

10. (Amended) The manufacturing process for a printed wiring board according to claim 5, characterized in that said organic layer is formed by repeatedly applying an organic agent constituted of one or constituted as a mixture of two or more selected

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from the group consisting of nitrogen-containing organic compounds, sulfur-containing organic compounds and carboxylic acids several times.

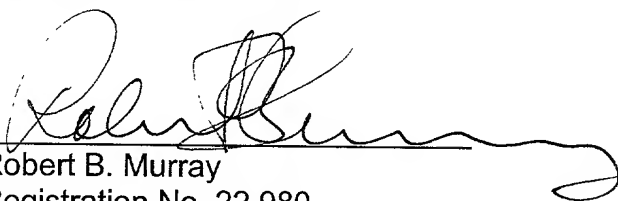
11. (Amended) The manufacturing process for a printed wiring board according to claim 5, characterized in that said organic layer is formed by alternately applying two organic agents or more selected from the group consisting of nitrogen-containing organic compounds, sulfur-containing organic compounds and carboxylic acids several time.

### REMARKS

Claims 1-11 are pending in this application. By this Amendment, claims 9, 10 and 11 are amended to delete multiple dependency. No new matter is contained in the amendments.

Please charge any fee deficiency or credit any overpayment to Deposit Account No. 01-2300.

Respectfully submitted,

  
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# Marked UP Claims

9. The manufacturing process for a printed wiring board according to (any of) claims 5 (to 8), characterized in that said organic layer is formed with one or two selected from the group consisting of nitrogen-containing organic compounds, sulfur-containing organic compounds and carboxylic acids.

10. The manufacturing process for a printed wiring board according to (any of) claims 5 (to 8), characterized in that said organic layer is formed by repeatedly applying an organic agent constituted of one or constituted as a mixture of two or more selected from the group consisting of nitrogen-containing organic compounds, sulfur-containing organic compounds and carboxylic acids several times.

11. The manufacturing process for a printed wiring board according to (any of) claims 5 (to 8), characterized in that said organic layer is formed by alternately applying two organic agents or more selected from the group consisting of nitrogen-containing organic compounds, sulfur-containing organic compounds and carboxylic acids several time.